# **Specification for Approval**

# PRODUCTNAME: OHEM128128-01 VER: A

CUSTOMER
APPROVED BY
DATE:

## **REVISION RECORD**

REV.	REVISION DESCRIPTION	REV. DATE	REMARK
X01	■ INITIAL RELEASE		
X02	<ul> <li>Modify definition of panel thickness</li> <li>Add lifetime specifications</li> <li>Modify D.C electrical characteristics</li> <li>Add panel electrical specifications</li> <li>Add application circuit</li> </ul>		Page5,6,7,8 & 16
A01	<ul> <li>Transfer from X version</li> <li>Add the information of module weight</li> <li>Modify seal color (white→black)</li> <li>Add the packing specification</li> </ul>		Page5,18& 19

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## 1. SCOPE

The purpose of this specification is to define the general provisions and quality requirements that apply to the supply of display cells manufactured by HES . This document, together with the Module Assembly Drawing, is the highest-level specification for this product. It describes the product, identifies supporting documents and contains specifications.

## 2. WARRANTY

HES warrants that the products delivered pursuant to this specification (or order) will conform to the agreed specifications for twelve (12) months from the shipping date ("Warranty Period"). HES is obligated to repair or replace the products which are found to be defective or inconsistent with the specifications during the Warranty Period without charge, on condition that the products are stored or used as the conditions specified in the specifications. Nevertheless, HES is not obligated to repair or replace the products without charge if the defects or inconsistency are caused by the force majeure or the reckless behaviors of the customer.

After the Warranty Period, all repairs or replacements of the products are subject to charge.

## 3. FEATURES

- Small molecular organic light emitting diode.
- Color : White
- Panel resolution : 128\*128
- Driver IC : SSD1327
- Excellent Quick response time : 10µs
- Extremely thin thickness for best mechanism design : 1.41 mm
- High contrast : 2000:1
- Wide viewing angle : 160°
- Strong environmental resistance.
- 8-bit 6800-series Parallel Interface, 8-bit 8080-series Parallel Interface, Serial Peripheral Interface, I<sup>2</sup>C Interface.
- Wide range of operating temperature : -40 to 70°C
- Anti-glare polarizer.

## 4. MECHANICAL DATA

		•	
NO	ITEM	SPECIFICATION	UNIT
1	Dot Matrix	128 x 128	dot
2	Dot Size	0.19 (W) x 0.19 (H)	mm <sup>2</sup>
3	Dot Pitch	0.21 (W) x 0.21 (H)	mm <sup>2</sup>
4	Aperture Rate	82	%
5	Active Area	26.86 (W) x 26.86 (H)	mm <sup>2</sup>
6	Panel Size	33.8 (W) x 36.5 (H)	mm <sup>2</sup>
7*	Panel Thickness	1.22 ± 0.1	mm
8	Module Size	33.8 (W) x 43.7 (H) x 1.41 (T)	mm <sup>3</sup>
9	Diagonal A/A size	1.5	inch
10	Module Weight	3.48 ± 10%	gram

\* Panel thickness includes substrate glass, cover glass and UV glue thickness.

## 5. MAXIMUM RATINGS

ITEM	MIN	MAX	UNIT	Condition	Remark
Supply Voltage ( $V_{CI}$ )	-0.3	4	V	Ta = 25°C	IC maximum rating
Supply Voltage (Vcc)	8	19	V	Ta = 25°C	IC maximum rating
Operating Temp.	-40	70	°C		0
Storage Temp	-40	85	°C		
Humidity		85	%		
Life Time	10,000	-	Hrs	100 cd/m <sup>2</sup> , 50% checkerboard	Note (1)
Life Time	11,000	-	Hrs	90 cd/m <sup>2</sup> , 50% checkerboard	Note (2)
Life Time	12,000	-	Hrs	80 cd/m <sup>2</sup> , 50% checkerboard	Note (3)

Note:

(A) Under Vcc = 15V, Ta = 25°C, 50% RH.

(B) Life time is defined the amount of time when the luminance has decayed to less than 50% of the initial measured luminance.

## (1) Setting of 100 cd/m<sup>2</sup>:

- Contrast setting : 0x9b
- Frame rate : 105Hz
- Duty setting : 1/128

(2) Setting of 90  $cd/m^2$  :

- Contrast setting : 0x77
- Frame rate : 105Hz
- Duty setting : 1/128

(3) Setting of 80  $cd/m^2$ :

- Contrast setting : 0x60
- Frame rate : 105Hz
- Duty setting : 1/128

## 6. ELECTRICAL CHARACTERISTICS

## 6.1 D.C ELECTRICAL CHARACTERISTICS

SYMBOL	PARAMETERS	TEST CONDITION	MIN	TYP	MAX	UNIT
	Driver power supply (for OLED panel)	-	14.5	15	15.5	V
I VCI	Low voltage power supply	-	2.6	-	3.5	V
V <sub>OH</sub>	High logic output level	lout=100 uA,	0.9* V <sub>CI</sub>	-	V <sub>CI</sub>	V
Vol	Low logic output level	lout=100uA,	0	_	0.1* V <sub>CI</sub>	V
Vih	High logic input level	lout=100uA,	0.8* V <sub>CI</sub>	_	Vci	V
VII	Low logic input level	lout=100uA,	0	-	0.2* V <sub>CI</sub>	V
Icc		V <sub>CI</sub> = 3.5V, V <sub>CC</sub> = 18V, Display ON,	External V <sub>DD</sub> = 2.5V	600	750	uA
		No panel attached, contrast = FF	Internal V <sub>DD</sub> = 2.5V	600	750	
I <sub>CI</sub>	V <sub>CI</sub> Supply Current	V <sub>CI</sub> = 3.5V, V <sub>CC</sub> = 18V, Display ON,	External V <sub>DD</sub> = 2.5V	35	50	uA
		No panel attached, contrast = FF	Internal V <sub>DD</sub> = 2.5V	95	120	
		Contrast=FF		300	370	uA
	Segment output	Contrast=AF	-	206	_	uA
ISEG	current Setting	Contrast=7F	-	150	-	uA
	$V_{CC}$ =18V, IREF=10uA	Contrast=3F	_	75	_	uA
		Contrast=1F	-	37.5	-	uA

## 6.2 ELECTRO-OPTICAL CHARACTERISTICS

ANEL LEED INIDAL O					
PARAMETER	MIN	TYP.	MAX	UNITS	COMMENTS
Normal mode current consumption	-	32	34	mA	All pixels on
Standby mode current consumption	-	3	4	mA	Standby mode 10% pixels on
Normal mode power consumption	-	480	510	mW	All pixels on
Standby mode power consumption	-	45	60	mW	Standby mode 10% pixels on
Pixel Luminance	70	90		cd/m <sup>2</sup>	Display Average
Standby Luminance		20		cd/m <sup>2</sup>	
CIEx (White)	0.24	0.28	0.32		CIE1931
CIEy (White)	0.28	0.32	0.36		CIE1931
Dark Room Contrast	2000:1				
Viewing Angle	160			degree	
Response Time		10		μs	

## PANEL ELECTRICAL SPECIFICATIONS

Normal mode condition :

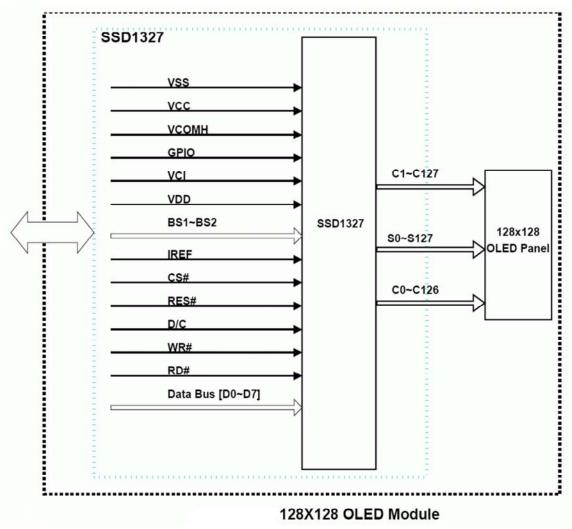
- Driving Voltage : 15V
- Contrast setting : 0x77
- Frame rate : 105Hz
- Duty setting : 1/128

Standby mode condition :

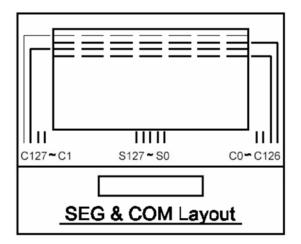
- Driving Voltage : 15V
- Contrast setting : 0x14
- Frame rate : 105Hz
- Duty setting : 1/128

## 7. INTERFACE

### 7.1 FUNCTION BLOCK DIAGRAM



## 7.2 PANEL LAYOUT DIAGRAM



## 7.3 PIN ASSIGNMENTS

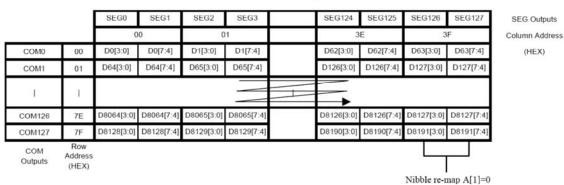
PIN NAME	PIN NO	DESCRIPTION
VSS	1	Ground.
VPP	2	Power supply for analog circuit.
VCOMH	3	Com Voltage Output. A capacitor should be connected between this pin and $V_{SS}$ .
VCI	4	Power supply for logic circuit.
VDD	5	A capacitor should be connected between this pin and Vss.
IREF	6	Reference current input pin. A resistor should be connected between this pin and V <sub>SS</sub> .
CS#	7	Chip select input.
RES#	8	Reset signal input. When it's low, initialization of SSD1327 is executed.
D/C	9	Data/ Command control. Pull high for write/read display data. Pull low for write command or read status.
D0	10	D0 will be the serial clock input
D1	11	D1 will be the serial data input

## 7.4 GRAPHIC DISPLAY DATA RAM ADDRESS MAP

The GDDRAM is a bit mapped static RAM holding the bit pattern to be displayed. The size of the RAM is 128x128x4 bits. For mechanical flexibility, re-mapping on both Segment and Common outputs can be selected by software. The GDDRAM address maps below tables show some examples on using the command "Set Re-map" A0h to re-map the GDDRAM. In the following tables, the lower nibble and higher nibble of D0, D1, D2 ... D8189, D8190, D8191 represent the 128x128 data bytes in the GDDRAM.

The GDDRAM map under the following condition:

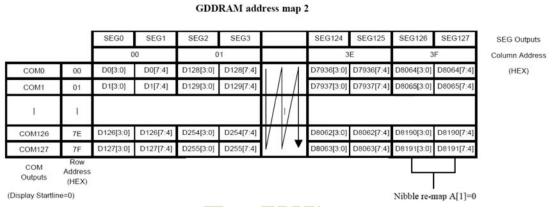
- Command "Set Re-map" A0h is set to: Disable Column Address Re-map (A[0]=0) Disable Nibble Re-map (A[1]=0) Enable Horizontal Address Increment (A[2]=0) Disable COM Re-map (A[4]=0)
- Display Start Line=00h
- Data byte sequence: D0, D1, D2 ... D8191



#### GDDRAM address map 1

The GDDRAM map under the following condition:

- Command "Set Re-map" A0h is set to: Disable Column Address Re-map (A[0]=0) Disable Nibble Re-map (A[1]=0) Enable Vertical Address Increment (A[2]=1) Disable COM Re-map (A[4]=0)
- Display Start Line=00h
- Data byte sequence: D0, D1, D2 ... D8191



The GDDRAM map under the following condition:

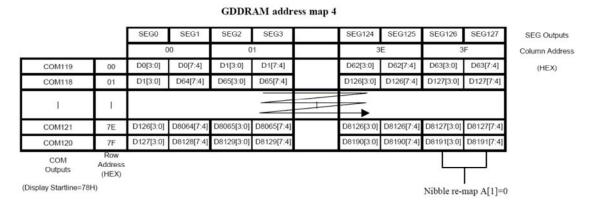
- Command "Set Re-map" A0h is set to: Enable Column Address Re-map (A[0]=1) Enable Nibble Re-map (A[1]=1) Enable Horizontal Address Increment (A[2]=0) Disable COM Re-map (A[4]=0)
- Display Start Line=00h
- Data byte sequence: D0, D1, D2 ... D8191

#### GDDRAM address map 3

		SEG0	SEG1	SEG2	SEG3		SEG124	SEG125	SEG126	SEG127	SEG Outputs
		3	F	3	ε		0	)1	C	0	Column Address
COM0	00	D63[7:4]	D63[3:0]	D62[7:4]	D62[3:0]		D1[7:4]	D1[3:0]	D0[7:4]	D0[3:0]	(HEX)
COM1	01	D127[7:4]	D127[3:0]	D126[7:4]	D126[3:0]		D65[7:4]	D65[3:0]	D64[7:4]	D64[3:0]	
1	I					1					
COM126	7E	D8127[7:4]	D8127[3:0]	D8126[7:4]	D8126[3:0]		D8065[7:4]	D8065[3:0]	D8064[7:4]	D8064[3:0]	
COM127	7F	D8191[7:4]	D8191[3:0]	D8190[7:4]	D8190[3:0]		D8129[7:4]	D8129[3:0]	D8128[7:4]	D8128[3:0]	
COM Outputs	Row Address (HEX)										
Display Startline=0)									Nibble re-r	nap A[1]=1	

The example in which the display start line register is set to 10h with the following condition:

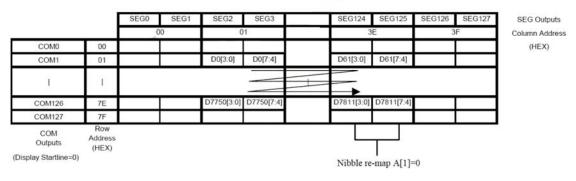
- Command "Set Re-map" A0h is set to: Disable Column Address Re-map (A[0]=0) Disable Nibble Re-map (A[1]=0) Enable Horizontal Address Increment (A[2]=0) Enable COM Re-map (A[4]=1)
- Display Start Line=78h (corresponds to COM119)
- Data byte sequence: D0, D1, D2 ... D8191



The GDDRAM map under the following condition:

- Command "Set Re-map" A0h is set to: Disable Column Address Re-map (A[0]=0) Disable Nibble Re-map (A[1]=0) Enable Horizontal Address Increment (A[2]=0) Disable COM Re-map (A[4]=0)
- Display Start Line=00h
- Column Start Address=01h
- Column End Address=3Eh
- Row Start Address=01h
- Row End Address=7Eh
- Data byte sequence: D0, D1, D2 ... D7811

#### GDDRAM address map 5

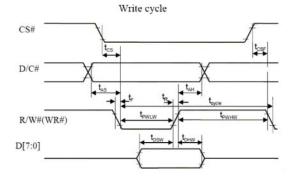


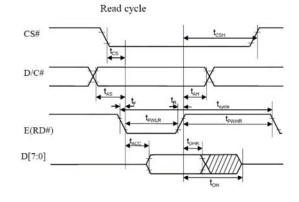
## 7.5 INTERFACE TIMING CHART

Symbol	Parameter	Min	Тур	Max	Unit
t <sub>cycle</sub>	Clock Cycle Time	300	-	-	ns
t <sub>AS</sub>	Address Setup Time	10	1411	-	ns
t <sub>AH</sub>	Address Hold Time	0	-	-	ns
t <sub>DSW</sub>	Write Data Setup Time	40		-	ns
t <sub>DHW</sub>	Write Data Hold Time	7	-	-	ns
t <sub>DHR</sub>	Read Data Hold Time	20	-	-	ns
t <sub>oH</sub>	Output Disable Time	-	-	70	ns
t <sub>ACC</sub>	Access Time	-	-	140	ns
t <sub>PWLR</sub>	Read Low Time	150		-	ns
t <sub>PWLW</sub>	Write Low Time	60	-	-	ns
t <sub>PWHR</sub>	Read High Time	60		-	ns
t <sub>PWHW</sub>	Write High Time	60	-	-	ns
t <sub>R</sub>	Rise Time	-	-	15	ns
t <sub>F</sub>	Fall Time	-	-	15	ns
t <sub>cs</sub>	Chip select setup time	0	-	-	ns
t <sub>CSH</sub>	Chip select hold time to read signal	0	-	-	ns
t <sub>CSF</sub>	Chip select hold time	20	-	-	ns

#### 8080-Series MCU Parallel Interface Timing Characteristics

#### 8080-series MCU parallel interface characteristics



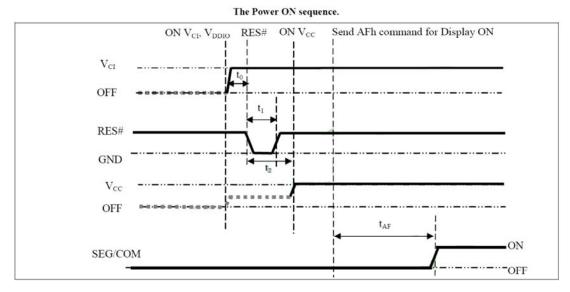


## 8. POWER ON / OFF SEQUENCE & APPLICATION CIRCUIT

## 8.1 POWER ON / OFF SEQUENCE

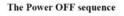
#### Power ON sequence:

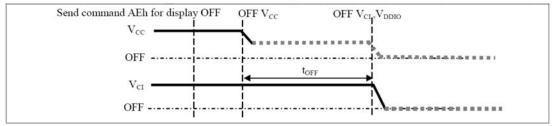
- 1. Power ON V<sub>CI</sub>.
- 2. After V<sub>CI</sub> becomes stable, set wait time at least 1ms ( $t_0$ ) for internal V<sub>DD</sub> become stable. Then set RES# pin LOW (logic low) for at least 100us ( $t_1$ )<sup>(4)</sup> and then HIGH (logic high).
- 3. After set RES# pin LOW (logic low), wait for at least 100us (t<sub>2</sub>). Then Power ON  $V_{CC}$ .<sup>(1)</sup>
- 4. After  $V_{CC}$  become stable, send command AFh for display ON. SEG/COM will be ON after 200ms( $t_{AF}$ ).



#### Power OFF sequence:

- 1. Send command AEh for display OFF.
- 2. Power OFF  $V_{CC}$ .<sup>(1), (2), (3)</sup>
- 3. Wait for t<sub>OFF</sub>. Power OFF V<sub>CI</sub>.(where Minimum t<sub>OFF</sub>=80ms<sup>(5)</sup>, Typical t<sub>OFF</sub>=100ms)

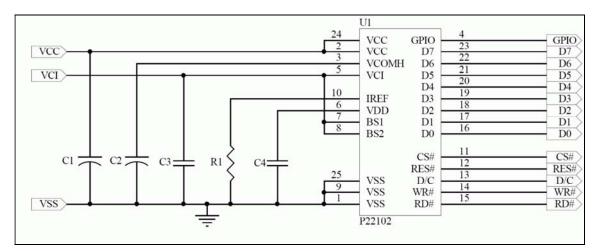




#### Note:

- (1) Since an ESD protection circuit is connected between  $V_{CI}$  and  $V_{CC}$ ,  $V_{CC}$  becomes lower than  $V_{CI}$  whenever  $V_{CI}$  is ON and  $V_{CC}$  is OFF as shown in the dotted line of  $V_{CC}$  in above figures.
- (2)  $V_{\text{CC}}$  should be kept disable when it is OFF.
- (3) Power pins (V<sub>Cl</sub>, V<sub>CC</sub>) can never be pulled to ground under any circumstance.
- (4) The register values are reset after  $t_1$ .
- (5)  $V_{CI}$  should not be Power OFF before  $V_{CC}$  Power OFF

## **8.2 APPLICATION CIRCUIT**



## Component:

- C1, C2: 4.7uF/35V(Tantalum type) or VISHAY (572D475X0025A2T)
- C3, C4: 1uF/16V(0603)
- R1: 1M ohm (0603) 1%

## This circuit is for 8080 8bits interface.

## 8.3 COMMAND TABLE

Refer to IC Spec.: SSD1327

## 9. RELIABILITY TEST CONDITIONS

No.	ltems	Specification	Quantity
1	High temp. (Non-operation)	85°C, 240hrs	5
2	High temp. (Operation)	70°C, 120hrs	5
3	Low temp. (Operation)	-40°C, 120hrs	5
4	High temp. / High humidity (Operation)	65°C, 90%RH, 120hrs	5
5	Thermal shock (Non-operation)	-40°C ~85°C (-40°C /30min; transit /3min; 85°C /30min; transit /3min) 1cycle: 66min, 100 cycles	5
6	Vibration	Frequency : 5~50HZ, 0.5G Scan rate : 1 oct/min Time : 2 hrs/axis Test axis : X, Y, Z	1 Carton
7	Drop	Height: 120cm Sequence : 1 angle \ 3 edges and 6 faces Cycles: 1	1 Carton
8	ESD (Non-operation)	Air discharge model, ±8kV, 10 times	5

## Test and measurement conditions

- 1. All measurements shall not be started until the specimens attain to temperature stability.
- 2. All-pixels-on is used as operation test pattern.
- 3. The degradation of Polarizer are ignored for item 1, 4 & 5.

## **Evaluation criteria**

- 1. The function test is OK.
- 2. No observable defects.
- 3. Luminance: > 50% of initial value.
- 4. Current consumption: within  $\pm$  50% of initial value.

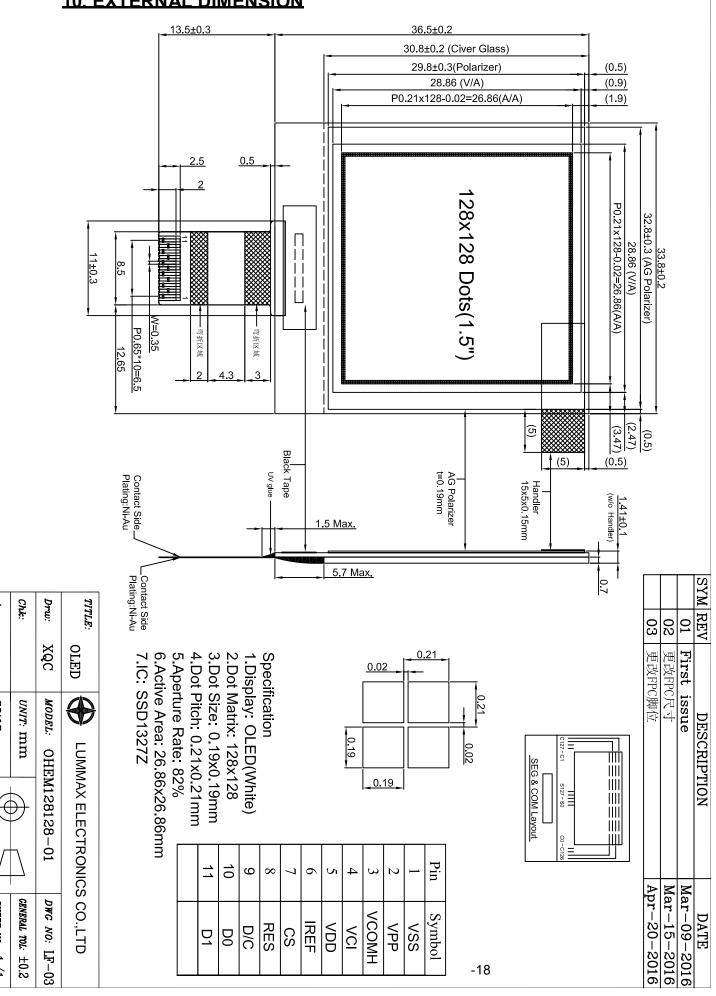
## **10. EXTERNAL DIMENSION**

Apv:

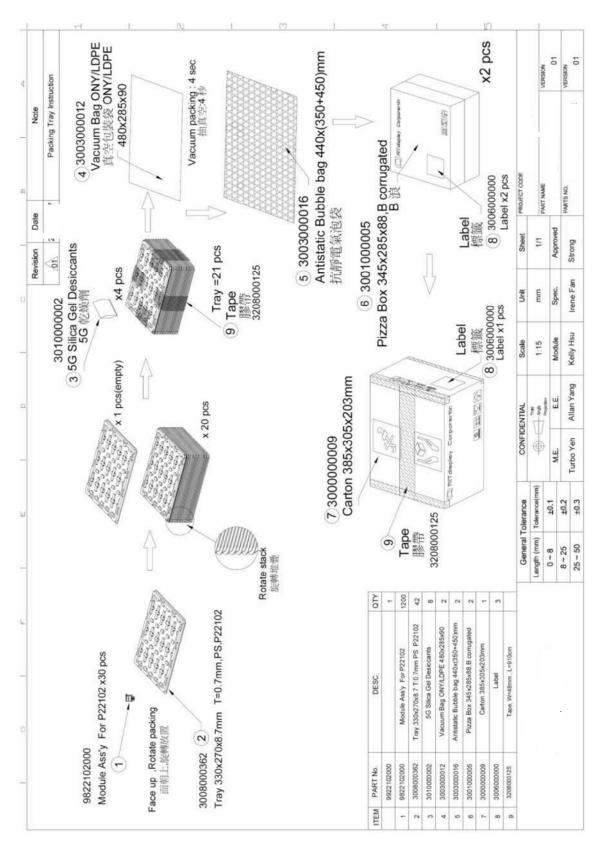
SCALE:

SHEET NO:

1/1



## **11. PACKING SPECIFICATION**



## 12. APPENDIXES

## **APPENDIX 1: DEFINITIONS**

## A. DEFINITION OF CHROMATICITY COORDINATE

The chromaticity coordinate is defined as the coordinate value on the CIE 1931 color chart for R, G, B, W.

## **B. DEFINITION OF CONTRAST RATIO**

The contrast ratio is defined as the following formula:

Contrast Ratio = Luminance of all pixels on measurement Luminance of all pixels off measurement

## C. DEFINITION OF RESPONSE TIME

The definition of turn-on response time Tr is the time interval between a pixel reaching 10% of steady state luminance and 90% of steady state luminance. The definition of turn-off response time Tf is the time interval between a pixel reaching 90% of steady state luminance and 10% of steady state luminance. It is shown in Figure 2.

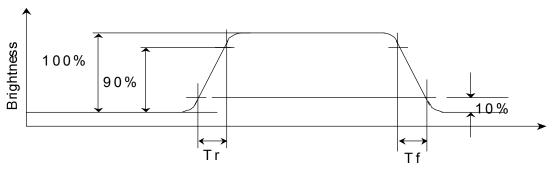


Figure 2 Response time

## D. DEFINITION OF VIEWING ANGLE

The viewing angle is defined as Figure 3. Horizontal and vertical (H & V) angles are determined for viewing directions where luminance varies by 50% of the perpendicular value.

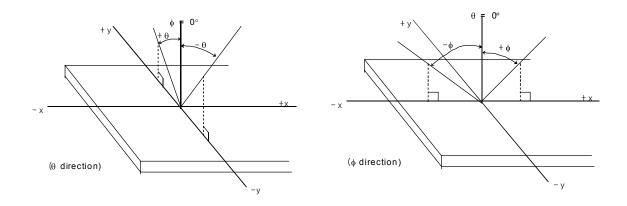
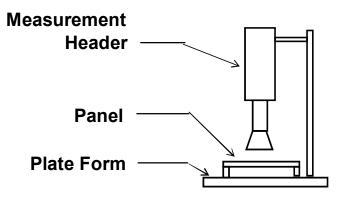


Figure 3 Viewing angle

## APPENDIX 2: MEASUREMENT APPARATUS

## A. LUMINANCE/COLOR COORDINATE

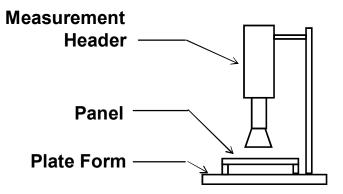
PHOTO RESEARCH PR-705, MINOLTA CS-100



PR-705 / MINOLTA CS-100 Color Analyzer

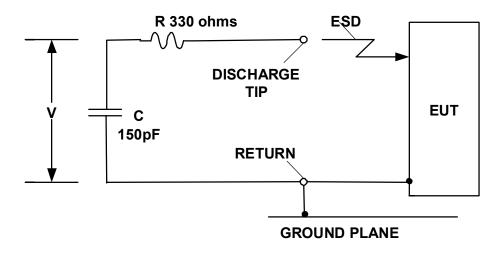
## B. CONTRAST / RESPONSE TIME / VIEWING ANGLE

WESTAR CORPORATION FPM-510



Westar FPM-510 Display Contrast / Response time / View angle Analyzer

## C. ESD ON AIR DISCHARGE MODE



## **APPENDIX 3: PRECAUTIONS**

## A. RESIDUE IMAGE

Because the pixels are lighted in different time, the luminance of active pixels may reduce or differ from inactive pixels. Therefore, the residue image will occur. To avoid the residue image, every pixel needs to be lighted up uniformly.